

Display Elektronik GmbH

DATA SHEET

TFT MODULE

DEM 240320R TMH-PW-N

3,2" TFT

Product Specification

Ver.: 2

04.02.2021

Revision History

Revision	Date	Originator	Detail	Remarks
0	16.12.2020	ZJW	Initial Release	
1	23.12.2020	MHI	Modify Block Diagram and Power Supply Modify Interface Pins Definition Modify Outline Drawing	P9 P10 P29
2	04.02.2021	MHI	Add Weight Add Current Consumption All Black Add Chromaticity Transmissive	P4 P5 P6

Table of Contents

No.	Item	Page
1.	General Description	4
2.	Module Parameter	4
3.	Absolute Maximum Ratings	4
4.	DC Characteristics	5
5.	Backlight Characteristic	5
5.1.	Backlight Characteristic	5
5.2.	Backlight Characteristic	5
6.	Optical Characteristics	6
6.1.	Optical Characteristics	6
6.2.	Definition of Response Time	6
6.3.	Definition of Contrast Ratio	7
6.4.	Definition of Viewing Angles	7
6.5.	Definition of Color Appearance	8
6.6.	Definition of Surface Luminance, Uniformity and Transmittance	8
7.	Block Diagram and Power Supply	9
8.	Interface Pins Definition	10
9.	AC Characteristics	12
10.	Quality Assurance	19
10.1.	Purpose	19
10.2.	Standard for Quality Test	19
10.3.	Nonconforming Analysis & Disposition	19
10.4.	Agreement Items	19
10.5.	Standard of the Product Visual Inspection	19
10.6.	Inspection Specification	20
10.7.	Classification of Defects	24
10.8.	Identification/marketing criteria	24
10.9.	Packing	24
11.	Reliability Specification	25
12.	Precautions and Warranty	26
12.1.	Safety	26
12.2.	Handling	26
12.3.	Storage	26
12.4.	Metal Pin (Apply to Products with Metal Pins)	26
12.5.	Operation	27
12.6.	Static Electricity	27
12.7.	Limited Warranty	27
13.	Outline Drawing	28

1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver Ics and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	3.2"	
LCD Type	TN TFT	
Display Mode	Transmissive /Normally white	
Resolution	240 RGB x 320	Pixels
View Direction	3 O'clock	Best Image
Gray Scale Inversion Direction	9 O'clock	
Module Outline	55.00 x 77.20 x 2.80	mm
Active Area	48.60 x 64.80	mm
Pixel Size	0.2025 x 0.2025	mm
Pixel Arrangement	RGB-Stripe	
Polarizer Surface Treatment	Anti-Glare	
Display Colors	262 K	
Interface	8/9/16/18 MPU Interface or 3-wire 9-bit Interface + RGB Interface or 4-wire 8-bit Interface + RGB Interface	
With or without touch panel	Without	
Driver IC	ILI9341V	-
Operating Temperature	-20 ~ 70	°C
Storage Temperature	-30 ~ 80	°C
Weight	TBD	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

$V_{SS}=0V$, $T_a=25^{\circ}C$

Item	Symbol	Min.	Max.	Unit
Supply Voltage	Logic	-0.3	4.6	V
	Analog	-0.3	4.6	V
Storage Temperature	T_{STG}	-30	+80	°C
Operating Temperature	T_{OP}	-20	+70	°C

Note 1: If T_a below $50^{\circ}C$, the maximal humidity is 90%RH, if T_a over $50^{\circ}C$, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around $-10^{\circ}C$, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item		Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	Logic	IOVCC	1.65	1.8/2.8	3.3	V
	Analog	VCC	2.4	2.8	3.3	V
Logic Low Input Voltage		V _{IL}	GND	-	0.3*IOVCC	V
Logic High Input Voltage		V _{IH}	0.7*IOVCC	-	IOVCC	V
Logic Low Output Voltage		V _{OL}	GND	-	0.2*IOVCC	V
Logic High Output Voltage		V _{OH}	0.8*IOVCC	-	IOVCC	V
Current Consumption All Black	Logic	I _{CC+ IIN}	-	7	-	mA
	Analog					

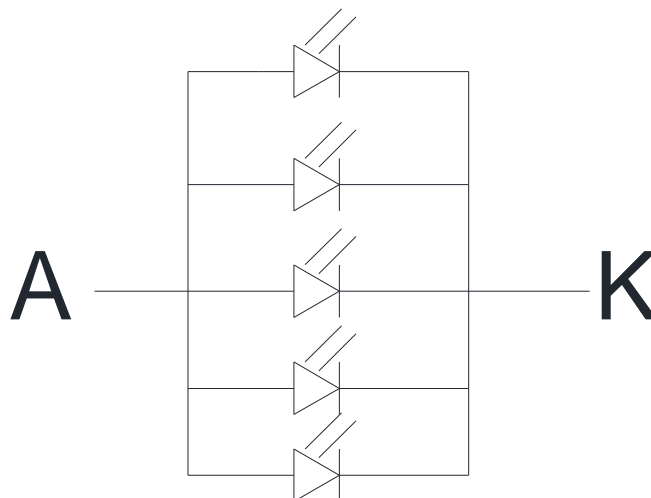
5. Backlight Characteristic

5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	T _a =25 °C, I _F =20mA/LED	2.8	3.2	3.4	V
Forward Current	I _F	T _a =25 °C, V _F =3.2V/LED	-	100		mA
Power Dissipation	P _D		-	320		mW
Uniformity	Avg		-	80	-	%
LED Lifetime (25°C)	-		20,000	30,000	-	Hrs
Drive Method	Constant current					
LED Configuration	5 White LEDs in parallel					

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.
 The environmental conducted under ambient air flow, at T_a=25± 2 °C, 60%RH± 5%,
 I_F=20mA/LED.

5.2. Backlight Characteristic



6. Optical Characteristics

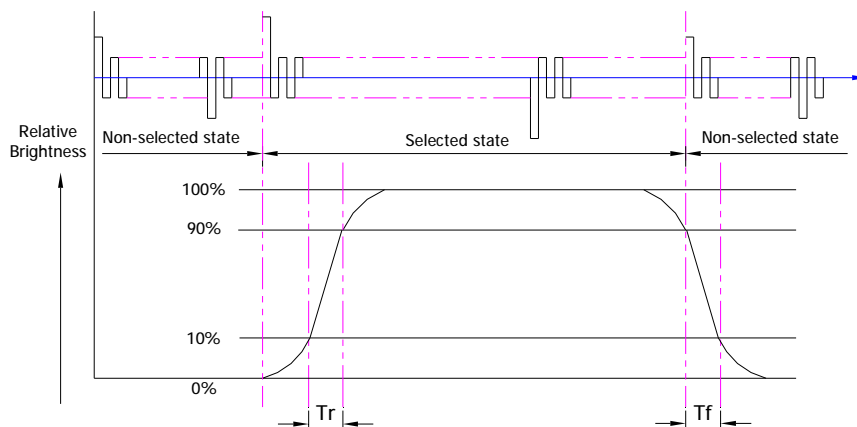
6.1. Optical Characteristics

Ta=25°C, VCC=2.8V

	Item	Symbol	Condition	Specification			Unit	
				Min.	Typ.	Max.		
Backlight On (Transmissive Mode)	Luminance On TFT($I_f=20\text{mA/LED}$)	Lv	Normally viewing angle $\theta_x = \phi_y = 0^\circ$	290	350	-	cd/m ²	
	Contrast Ratio(See 6.3)	CR		300	600	-		
	Response Time (See 6.2)	TR+TF		-	25	50	ms	
	Chromaticity Transmissive (See 6.5)	Red	XR	Center CR≥10	0.571	0.621	0.671	
			YR		0.312	0.362	0.412	
		Green	XG		0.255	0.305	0.355	
			YG		0.586	0.636	0.686	
		Blue	XB		0.095	0.145	0.195	
			YB		0.040	0.090	0.140	
	White	XW	0.217	0.267	0.317			
YW		0.281	0.331	0.381				
Viewing Angle (See 6.4)	Horizontal	θ_{x+}	Center CR≥10	15	25	-	Deg.	
		θ_{x-}		35	45	-		
	Vertical	ϕ_{y+}		35	45	-		
		ϕ_{y-}		35	45	-		
NTSC Ratio(Gamut)				-	58	-	%	

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

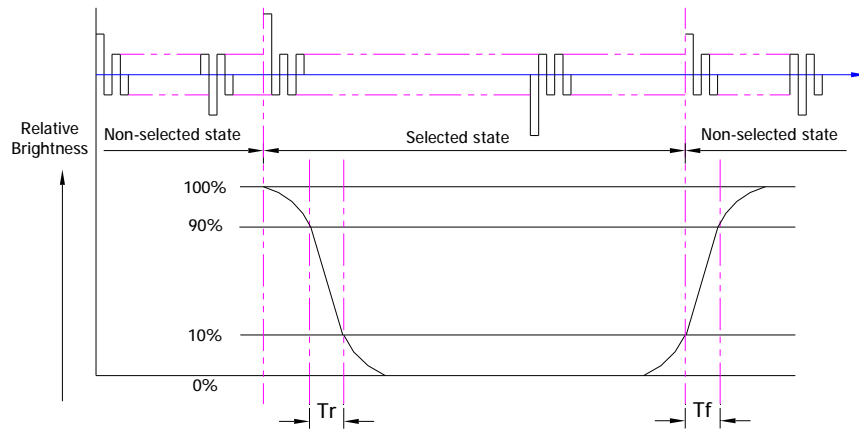


Tr is the time it takes to change from non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change from non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

6.3. Definition of Contrast Ratio

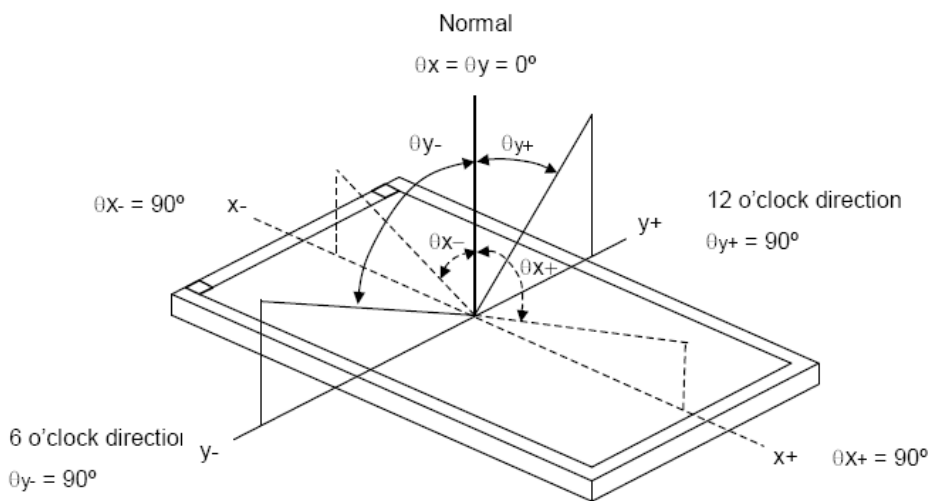
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test Pattern	A: All Pixels white
	B: All Pixel black
Contrast Setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



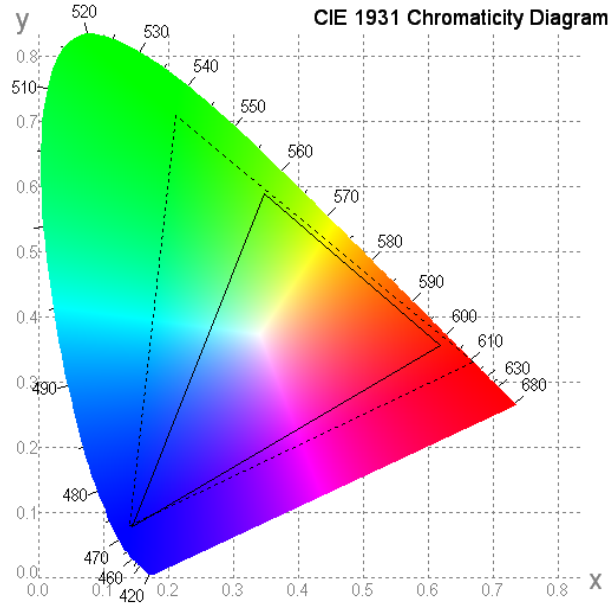
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

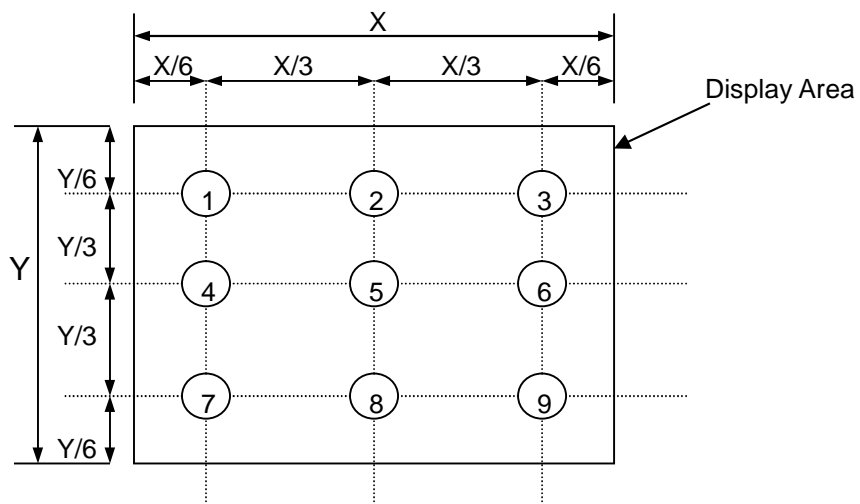
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: $L_v = \text{average} (L_{P1}:L_{P9})$

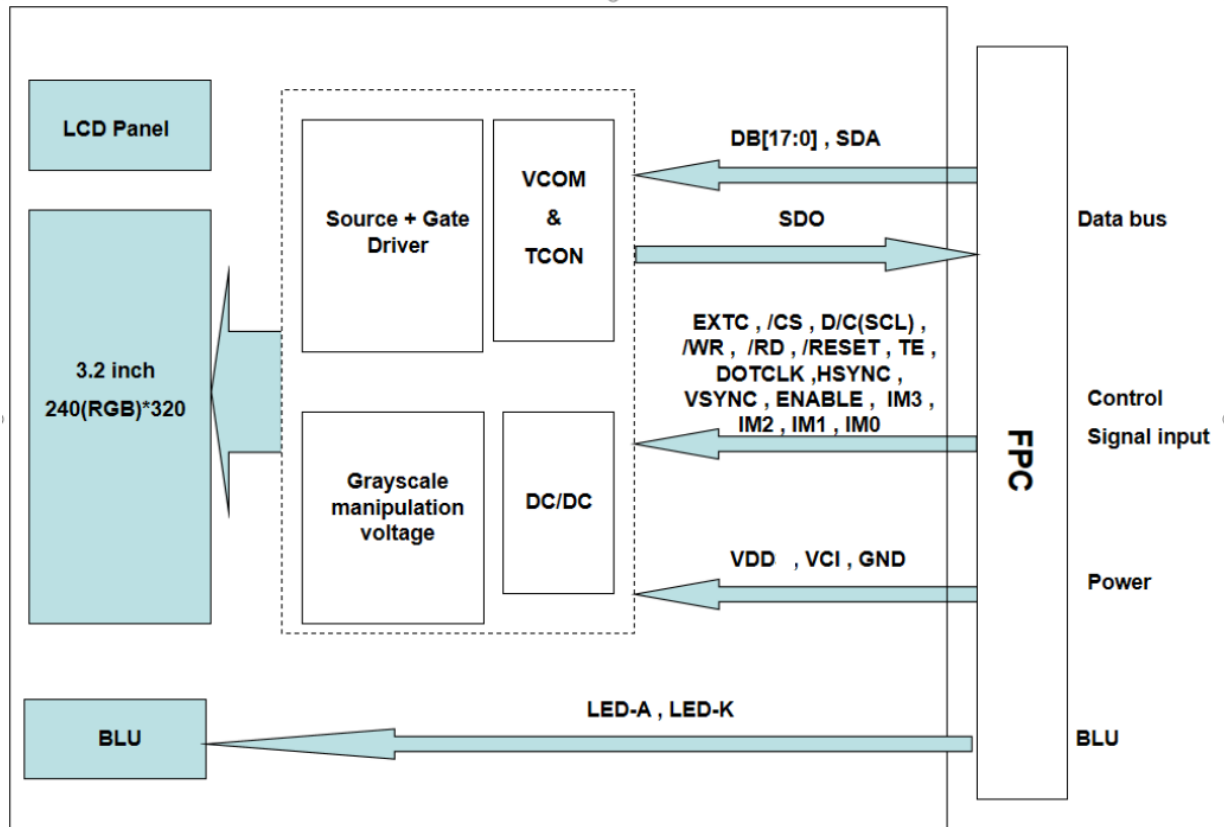
6.6.2. Uniformity = $\text{Minimal} (L_{P1}:L_{P9}) / \text{Maximal} (L_{P1}:L_{P9}) * 100\%$

6.6.3. Transmittance = $L_v \text{ on LCD} / L_v \text{ on Backlight} * 100\%$

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



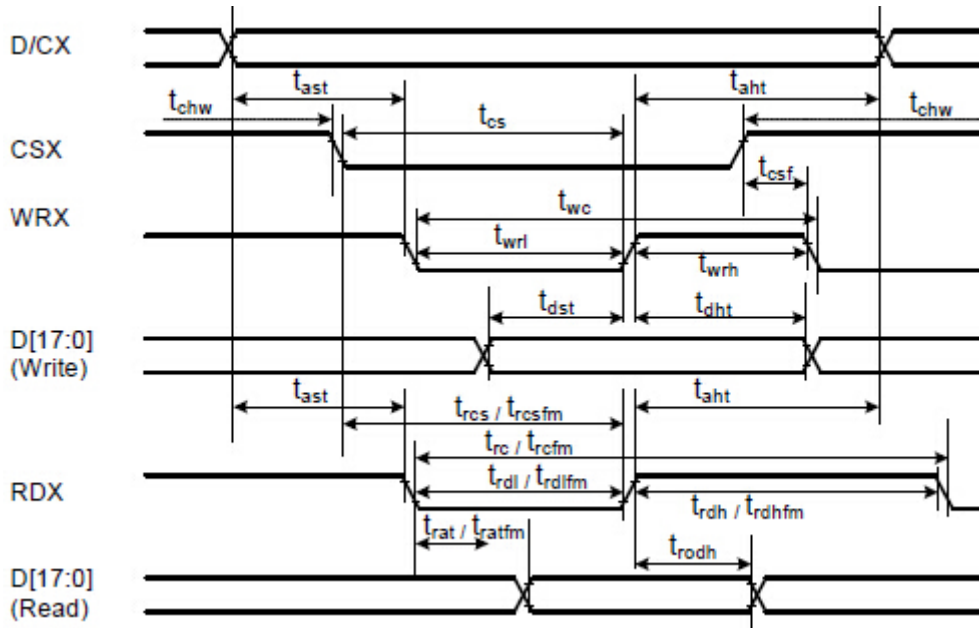
8. Interface Pins Definition

No.	Symbol	Function
1	EXTC	Extended command set enable. High: extended command set is accepted. EXTC must be set "H" to read/write extended registers.
2	IOVCC(1.8/2.8V)	Digital Supply Power.
3	VCC(2.8V)	Analog Supply Power.
4	/CS	Chip Select Signal (Low: active).
5	D/C(SCL)	D/C: Data/Commander Selection. SCL: Serial clock in 3-wire 9-bit/4-wire 8-bit serial data interface.
6	/WR	8080-system: Serves as Write Signal. 4-line system: Serves as the selector of command or parameter.
7	/RD	Read Signal.
8	/RESET	Reset Signal.
9	DB0	Data Bus.
10	DB1	Data Bus.
11	DB2	Data Bus.
12	DB3	Data Bus.
13	DB4	Data Bus.
14	DB5	Data Bus.
15	DB6	Data Bus.
16	DB7	Data Bus.
17	DB8	Data Bus.
18	DB9	Data Bus.
19	DB10	Data Bus.
20	DB11	Data Bus.
21	DB12	Data Bus.
22	DB13	Data Bus.
23	DB14	Data Bus.
24	DB15	Data Bus.
25	DB16	Data Bus.
26	DB17	Data Bus.
27	SDA	SPI interface input pin.
28	SDO	SPI interface output pin.
29	TE	Tearing effect output pin to synchronize MPU to frame writing, active by S/W command.
30	DOTCLK	Pixel clock signal in RGB I/F mode.
31	VSYNC	Vertical sync. Signal in RGB I/F mode.
32	HSYNC	Horizontal sync. Signal in RGB I/F mode.
33	ENABLE	Data enable signal in RGB I/F mode.

34-37	IM0-IM3	IM3	IM2	IM1	IM0	MPU interface Mode	DB pin	
							Register	Gram
							0	0
0	0	0	1	80 MCU 16-bit bus interface I	DB[7:0]	DB[15:0]		
0	0	1	0	80 MCU 9-bit bus interface I	DB[7:0]	DB[8:0]		
0	0	1	1	80 MCU 18-bit bus interface I	DB[7:0]	DB[17:0]		
0	1	0	1	3-wire 9-bit data Serial interface I	SDA: in/out			
0	1	1	0	4-wire 8-bit data Serial interface I	SDA: in/out			
1	0	0	0	80 MCU 16-bit bus interface II	DB[8:1]	DB[8:1] DB[17:10]		
1	0	0	1	80 MCU 8-bit bus interface II	DB[17:10]	DB[17:10]		
1	0	1	0	80 MCU 18-bit bus interface II	DB[8:1]	DB[17:0]		
1	0	1	1	80 MCU 9-bit bus interface II	DB[17:10]	DB[17:9]		
1	1	0	1	3-wire 9-bit data Serial interface II	SDI: in SDO: out			
1	1	1	0	4-wire 8-bit data Serial interface II	SDI: in SDO: out			
38	NC(YD)	No connection.						
39	NC(XR)	No connection.						
40	NC(YU)	No connection.						
41	NC(XL)	No connection.						
42	LED-A	LED Anode.						
43	LED-K	LED Cathode.						
44	GND	Ground.						
45	GND	Ground.						

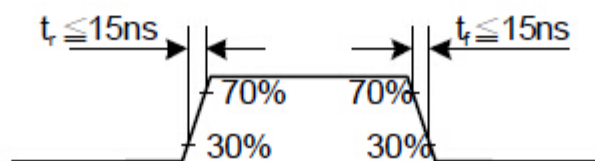
9. AC Characteristics

9.1 Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080-I system)

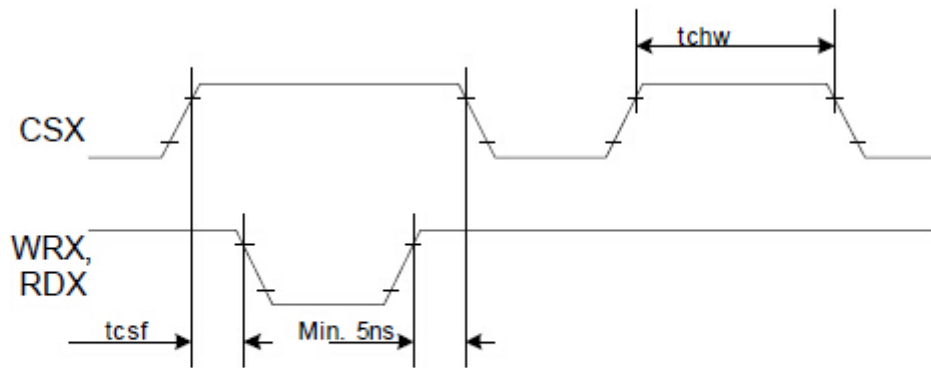


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: $T_a = -30$ to 70 °C, $V_{DDI}=1.65V$ to $3.3V$, $V_{CI}=2.5V$ to $3.3V$, $V_{SS}=0V$

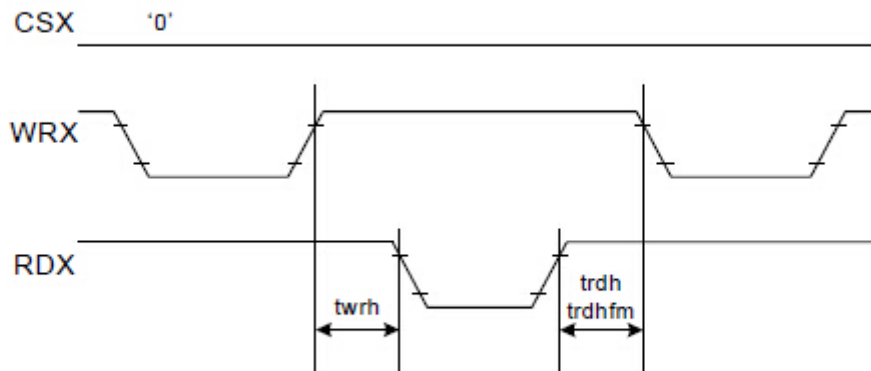


CSX timings :



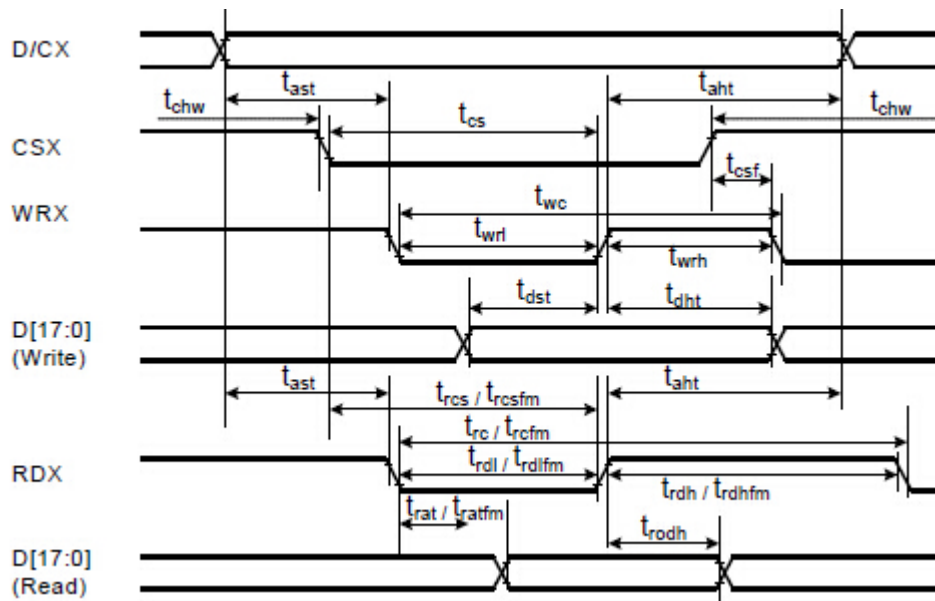
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



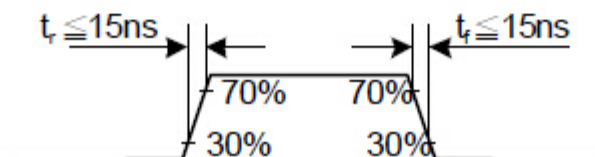
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

9.2 Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080-II system)

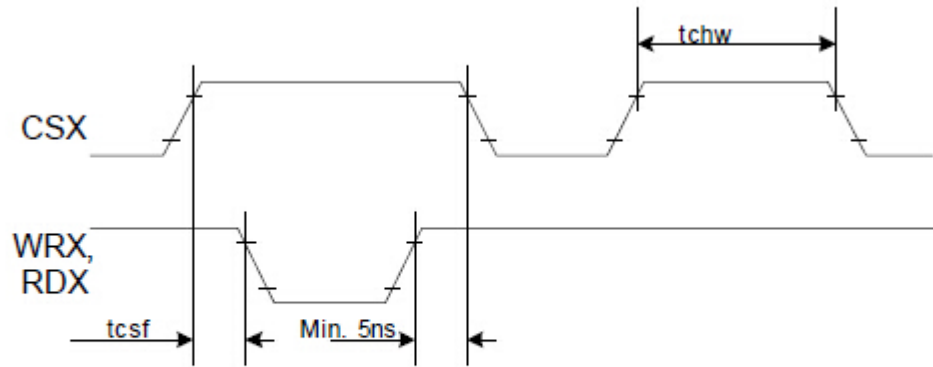


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trodh	Read output disable time	20	80	ns	

Note: $T_a = -30$ to 70 °C, $V_{DDI}=1.65V$ to $3.3V$, $V_{CI}=2.5V$ to $3.3V$, $V_{SS}=0V$.

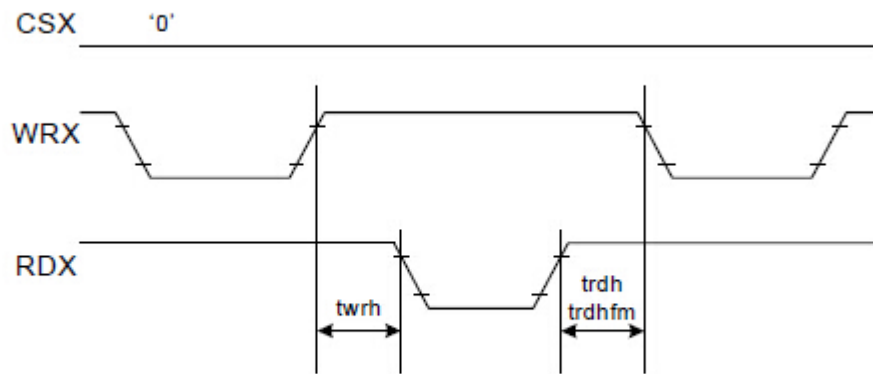


CSX timings :



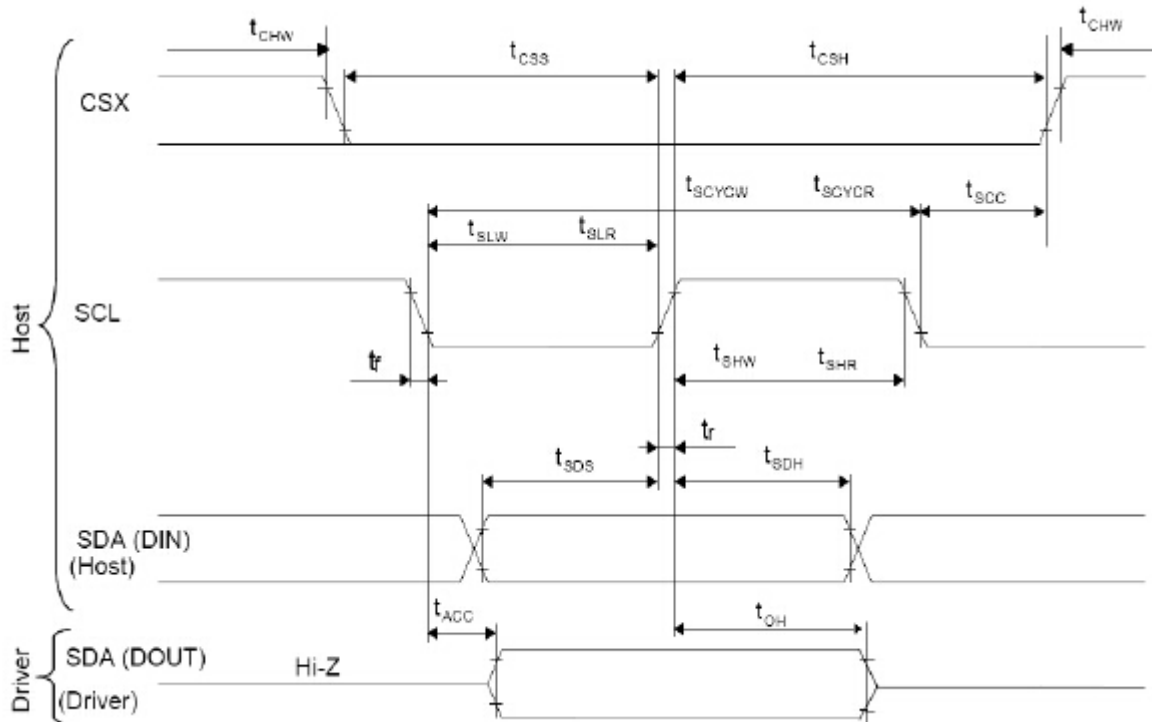
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



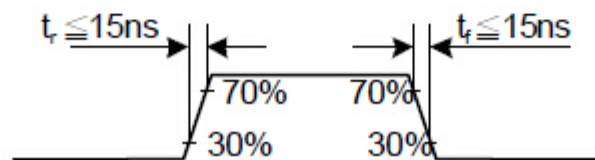
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

9.3 Display Serial Interface Timing Characteristics (3-line SPI system)

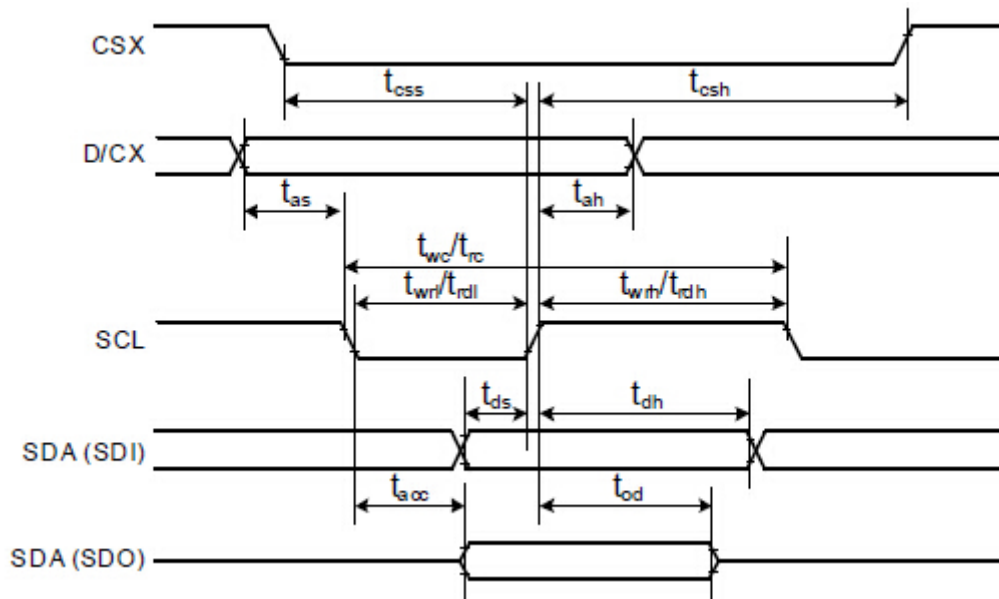


Signal	Symbol	Parameter	min	max	Unit	Description
SCL	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL "H" Pulse Width (Write)	40	-	ns	
	tslw	SCL "L" Pulse Width (Write)	40	-	ns	
	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	-	ns	
	tslr	SCL "L" Pulse Width (Read)	60	-	ns	
SDA / SDI (Input)	tsds	Data setup time (Write)	30	-	ns	
	tsdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	
	toh	Output disable time (Read)	10	50	ns	
CSX	tsc	SCL-CSX	20	-	ns	
	tchw	CSX "H" Pulse Width	40	-	ns	
	tcss	CSX-SCL Time	60	-	ns	
	tcs		65	-	ns	

Note: $T_a = 25\text{ }^\circ\text{C}$, $V_{DDI}=1.65\text{V to }3.3\text{V}$, $V_{CI}=2.5\text{V to }3.3\text{V}$, $AGND=VSS=0\text{V}$

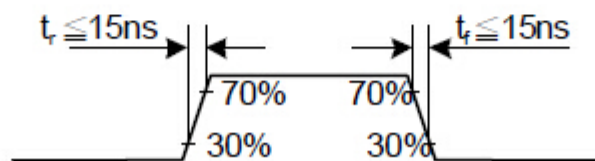


9.4 Display Serial Interface Timing Characteristics (4-line SPI system)

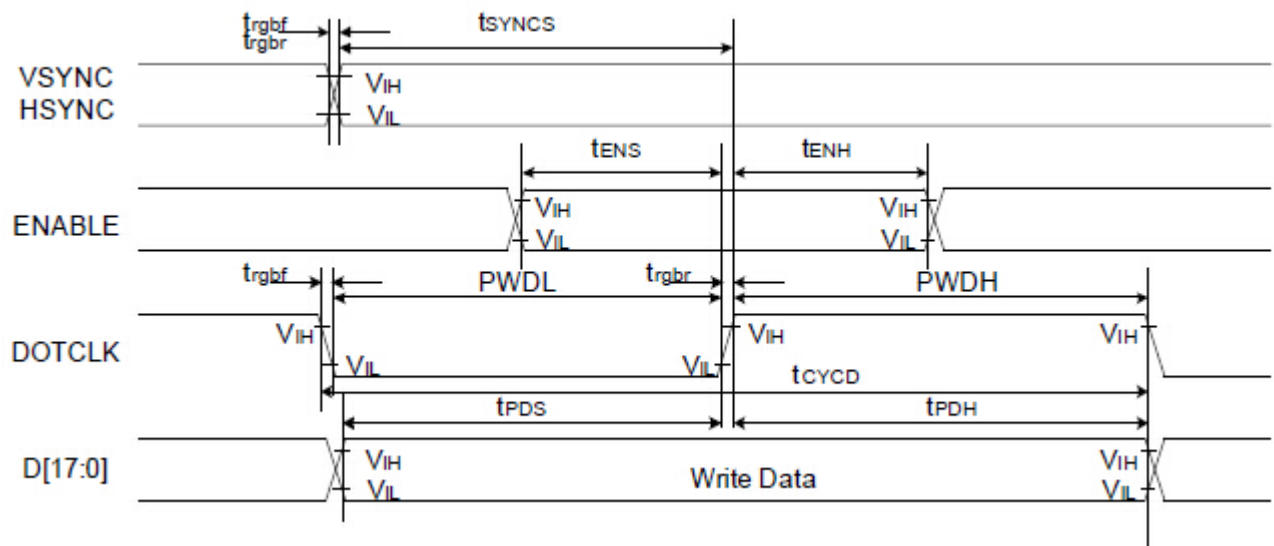


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	t_{css}	Chip select time (Write)	40	-	ns	
	t_{csh}	Chip select hold time (Read)	40	-	ns	
SCL	t_{wc}	Serial clock cycle (Write)	100	-	ns	
	t_{wrh}	SCL "H" pulse width (Write)	40	-	ns	
	t_{wrl}	SCL "L" pulse width (Write)	40	-	ns	
	t_{rc}	Serial clock cycle (Read)	150	-	ns	
	t_{rdh}	SCL "H" pulse width (Read)	60	-	ns	
	t_{rdl}	SCL "L" pulse width (Read)	60	-	ns	
D/CX	t_{as}	D/CX setup time	10	-		
	t_{ah}	D/CX hold time (Write / Read)	10	-		
SDA / SDI (Input)	t_{ds}	Data setup time (Write)	30	-	ns	
	t_{dh}	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	t_{acc}	Access time (Read)	10	-	ns	For maximum CL=30pF
	t_{od}	Output disable time (Read)	10	50	ns	For minimum CL=8pF

Note: $T_a = 25\text{ }^\circ\text{C}$, $V_{DDI}=1.65\text{V to }3.3\text{V}$, $V_{CI}=2.5\text{V to }3.3\text{V}$, $AGND=VSS=0\text{V}$

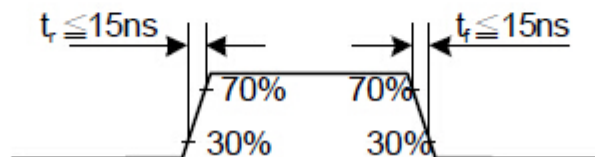


9.5 Parallel 18/16/6-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description	
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode	
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns		
DE	t_{ENS}	DE setup time	15	-	ns		
	t_{ENH}	DE hold time	15	-	ns		
D[17:0]	t_{POS}	Data setup time	15	-	ns		
	t_{PDH}	Data hold time	15	-	ns		
DOTCLK	PWDH	DOTCLK high-level period	15	-	ns		
	PWDL	DOTCLK low-level period	15	-	ns		
	t_{CYCD}	DOTCLK cycle time	100	-	ns		
	t_{rgbr}, t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns		
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns		6-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns		
DE	t_{ENS}	DE setup time	15	-	ns		
	t_{ENH}	DE hold time	15	-	ns		
D[17:0]	t_{POS}	Data setup time	15	-	ns		
	t_{PDH}	Data hold time	15	-	ns		
DOTCLK	PWDH	DOTCLK high-level pulse period	15	-	ns		
	PWDL	DOTCLK low-level pulse period	15	-	ns		
	t_{CYCD}	DOTCLK cycle time	50	-	ns		
	t_{rgbr}, t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns		

Note: $T_a = -30$ to 70 °C, $V_{DDI}=1.65V$ to $3.3V$, $V_{CI}=2.5V$ to $3.3V$, $AGND=VSS=0V$



10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2.Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3.Nonconforming Analysis & Disposition

10.3.1. Nonconforming analysis:

10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

10.3.2. Disposition of nonconforming:

10.3.2.1. Non-conforming product over PPM level will be replaced.

10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

10.4.1. There is any discrepancy in standard of quality assurance.

10.4.2. Additional requirement to be added in product specification.

10.4.3. Any other special problem.

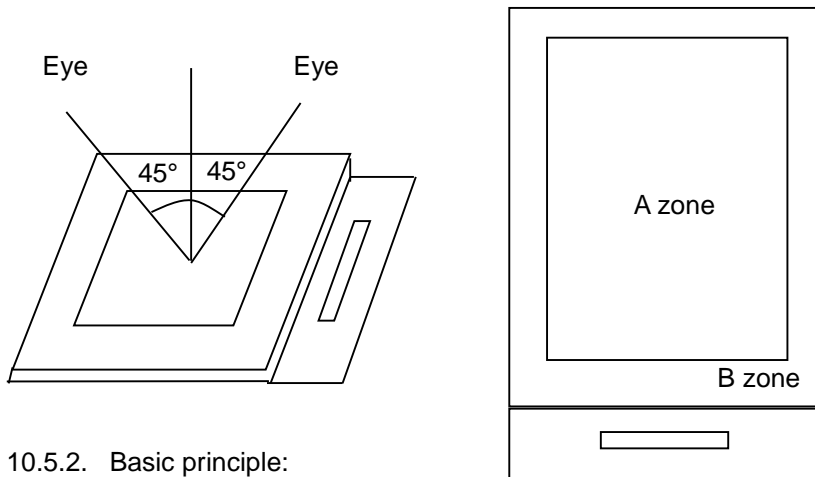
10.5.Standard of the Product Visual Inspection

10.5.1. Appearance inspection:

10.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



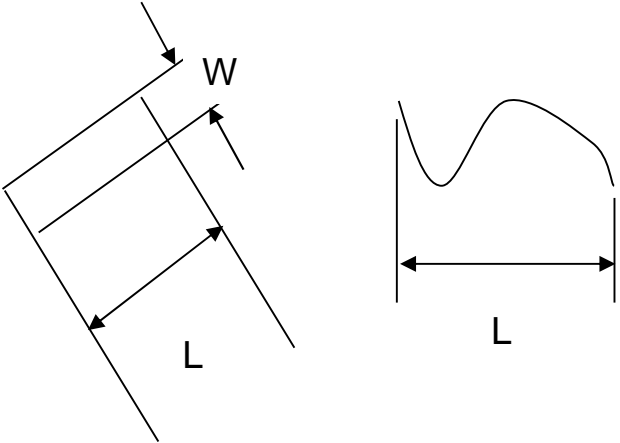
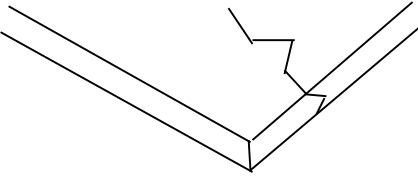
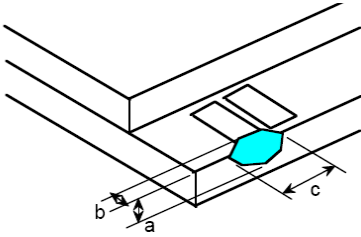
10.5.2. Basic principle:

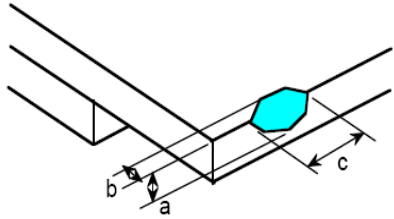
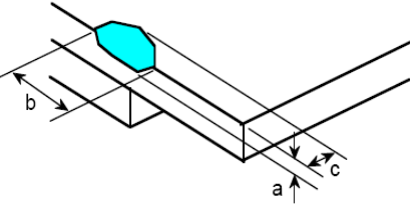
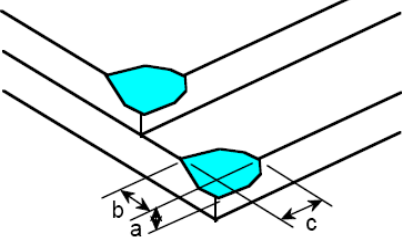
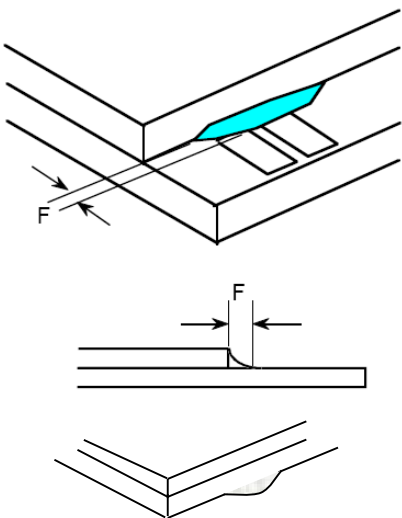
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

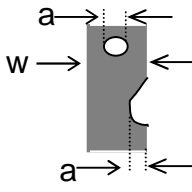
10.5.2.2. New item must be added on time when it is necessary.

10.6. Inspection Specification

No.	Item	Criteria (Unit: mm)																		
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	<p>$\phi = (a + b) / 2$</p> <table border="1"> <thead> <tr> <th>Size</th> <th>Area</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$\phi \leq 0.10$</td> <td></td> <td>Ignore</td> </tr> <tr> <td>$0.10 < \phi \leq 0.15$</td> <td></td> <td>2</td> </tr> <tr> <td>$0.15 < \phi \leq 0.25$</td> <td></td> <td>1</td> </tr> <tr> <td>$0.25 < \phi$</td> <td></td> <td>0</td> </tr> <tr> <td>Total</td> <td></td> <td>2 no include $\phi \leq 0.10$</td> </tr> </tbody> </table> <p>Distance between 2 defects should more than 3mm apart.</p>	Size	Area	Acc. Qty	$\phi \leq 0.10$		Ignore	$0.10 < \phi \leq 0.15$		2	$0.15 < \phi \leq 0.25$		1	$0.25 < \phi$		0	Total		2 no include $\phi \leq 0.10$
Size	Area	Acc. Qty																		
$\phi \leq 0.10$		Ignore																		
$0.10 < \phi \leq 0.15$		2																		
$0.15 < \phi \leq 0.25$		1																		
$0.25 < \phi$		0																		
Total		2 no include $\phi \leq 0.10$																		
02	Electrical Defect (Minor defect)	<table border="1"> <thead> <tr> <th></th> <th>Display Area</th> <th>Total</th> <th></th> </tr> </thead> <tbody> <tr> <td>Bright dot</td> <td>0</td> <td>0</td> <td rowspan="3">Note1</td> </tr> <tr> <td>Dark dot</td> <td>$N \leq 2$</td> <td>$N \leq 2$</td> </tr> <tr> <td>Total dot</td> <td>$N \leq 2$</td> <td>$N \leq 2$</td> </tr> <tr> <td>Mura</td> <td colspan="2">Not visible through 5% ND filters.</td> <td>Note 2</td> </tr> </tbody> </table> <p>Remark: 1. Bright dot caused by scratch and foreign object accords to item 1.</p>		Display Area	Total		Bright dot	0	0	Note1	Dark dot	$N \leq 2$	$N \leq 2$	Total dot	$N \leq 2$	$N \leq 2$	Mura	Not visible through 5% ND filters.		Note 2
	Display Area	Total																		
Bright dot	0	0	Note1																	
Dark dot	$N \leq 2$	$N \leq 2$																		
Total dot	$N \leq 2$	$N \leq 2$																		
Mura	Not visible through 5% ND filters.		Note 2																	

<p>03</p>	<p>Black and White line Scratch Foreign material (Line type) (Minor defect)</p>	 <table border="1" data-bbox="628 640 1254 949"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>/</td> <td>$W \leq 0.03$</td> <td>Ignore</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> <td>3</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.05 < W \leq 0.10$</td> <td>2</td> </tr> <tr> <td>/</td> <td>$0.1 < W$</td> <td>0</td> </tr> <tr> <td colspan="2">Total</td> <td>3</td> </tr> </tbody> </table> <p>Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.</p>	Length	Width	Acc. Qty	/	$W \leq 0.03$	Ignore	$L \leq 2.5$	$0.03 < W \leq 0.05$	3	$L \leq 2.5$	$0.05 < W \leq 0.10$	2	/	$0.1 < W$	0	Total		3
Length	Width	Acc. Qty																		
/	$W \leq 0.03$	Ignore																		
$L \leq 2.5$	$0.03 < W \leq 0.05$	3																		
$L \leq 2.5$	$0.05 < W \leq 0.10$	2																		
/	$0.1 < W$	0																		
Total		3																		
<p>04</p>	<p>Glass Crack (Minor defect)</p>	 <p>Crack is potential to enlarge, any type is not allowed.</p>																		
<p>05</p>	<p>Glass Chipping Pad Area: (Minor defect)</p> 	<table border="1" data-bbox="868 1532 1342 1704"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c > 3.0, b < 1.0$</td> <td>1</td> </tr> <tr> <td>$c < 3.0, b < 1.0$</td> <td>3</td> </tr> <tr> <td colspan="2">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$											
Length and Width	Acc. Qty																			
$c > 3.0, b < 1.0$	1																			
$c < 3.0, b < 1.0$	3																			
$a < \text{Glass Thickness}$																				

<p>06</p>	<p>Glass Chipping Rear of Pad Area: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c > 3.0, b < 1.0$</td> <td>1</td> </tr> <tr> <td>$c < 3.0, b < 1.0$</td> <td>2</td> </tr> <tr> <td>$c < 3.0, b < 0.5$</td> <td>4</td> </tr> <tr> <td colspan="2" style="text-align: center;">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
<p>07</p>	<p>Glass Chipping Except Pad Area: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c > 3.0, b < 1.0$</td> <td>1</td> </tr> <tr> <td>$c < 3.0, b < 1.0$</td> <td>2</td> </tr> <tr> <td>$c < 3.0, b < 0.5$</td> <td>4</td> </tr> <tr> <td colspan="2" style="text-align: center;">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
<p>08</p>	<p>Glass Corner Chipping: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c < 3.0, b < 3.0$</td> <td>Ignore</td> </tr> <tr> <td colspan="2" style="text-align: center;">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												
<p>09</p>	<p>Glass Burr: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$F < 1.0$</td> <td>Ignore</td> </tr> </tbody> </table> <p>Glass burr don't affect assemble and module dimension.</p>	Length	Acc. Qty	$F < 1.0$	Ignore						
Length	Acc. Qty											
$F < 1.0$	Ignore											

<p>10</p>	<p>FPC Defect: (Minor defect)</p> 	<p>10.1 Dent, pinhole width $a < w/3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.</p>										
<p>11</p>	<p>Bubble on Polarizer (Minor defect)</p>	<table border="1"> <thead> <tr> <th>Diameter</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$\varphi \leq 0.20$</td> <td>Ignore</td> </tr> <tr> <td>$0.20 < \varphi \leq 0.30$</td> <td>4</td> </tr> <tr> <td>$0.30 < \varphi \leq 0.50$</td> <td>1</td> </tr> <tr> <td>$0.50 < \varphi$</td> <td>None</td> </tr> </tbody> </table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
<p>12</p>	<p>Dent on Polarizer (Minor defect)</p>	<table border="1"> <thead> <tr> <th>Diameter</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$\varphi \leq 0.20$</td> <td>Ignore</td> </tr> <tr> <td>$0.20 < \varphi \leq 0.30$</td> <td>4</td> </tr> <tr> <td>$0.30 < \varphi \leq 0.50$</td> <td>1</td> </tr> <tr> <td>$0.50 < \varphi$</td> <td>None</td> </tr> </tbody> </table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
<p>13</p>	<p>Bezel</p>	<p>13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.</p>										
<p>14</p>	<p>PCB</p>	<p>14.1 No distortion or contamination on PCB terminals. 14.2 All components on PCB must same as documented on the BOM/component layout. 14.3 Follow IPC-A-600F.</p>										
<p>15</p>	<p>Soldering</p>	<p>Follow IPC-A-610C standard</p>										
<p>16</p>	<p>Electrical Defect (Major defect)</p>	<p>The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.</p>										

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

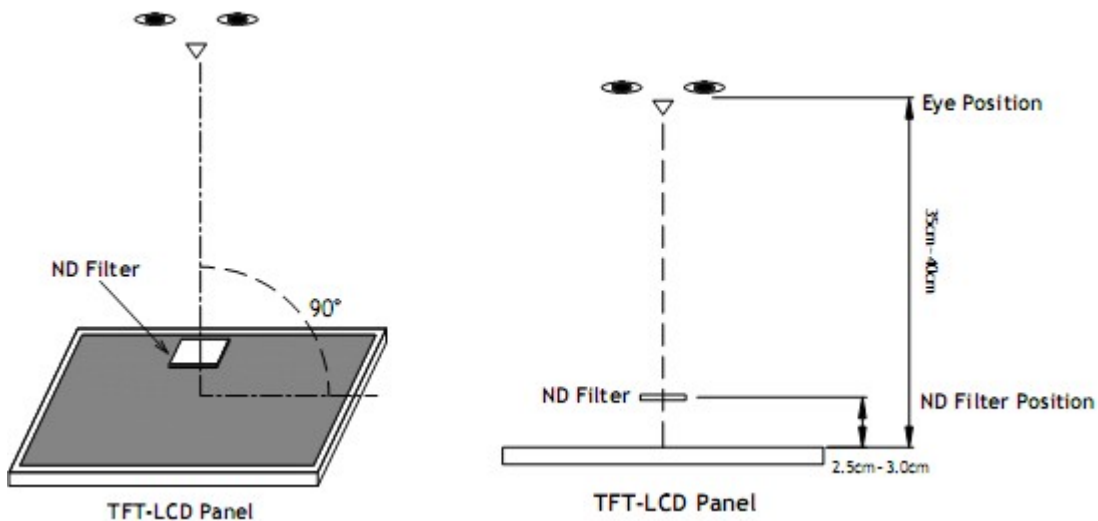
10.8. Identification/marketing criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm ± 50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm ± 50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1-2008
3	High Humidity Storage	50°C, 90%RH, 96Hrs	2	GB/T2423.3-2016
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test Storage	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.22-2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14-2009
8	Electrical Static Discharge	Air: ± 8 kV 150pF/330 Ω 5 times Contact: ± 4 kV 150pF/330 Ω 5 times	2	GB/T17626.2-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8-1995

Note1. No deflection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2.Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4.Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

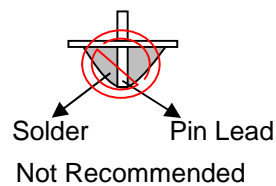
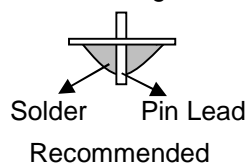
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

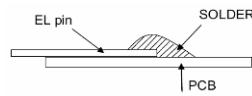
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

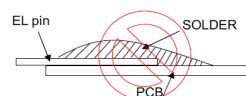
12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting

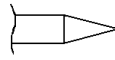


Recommended

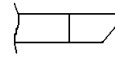


Not Recommended

12.4.2.7. The type of the solder iron:

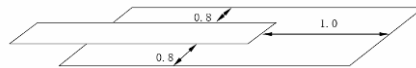


Recommended



Not Recommended

12.4.2.8. Solder Pad



12.5.Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. *Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.*

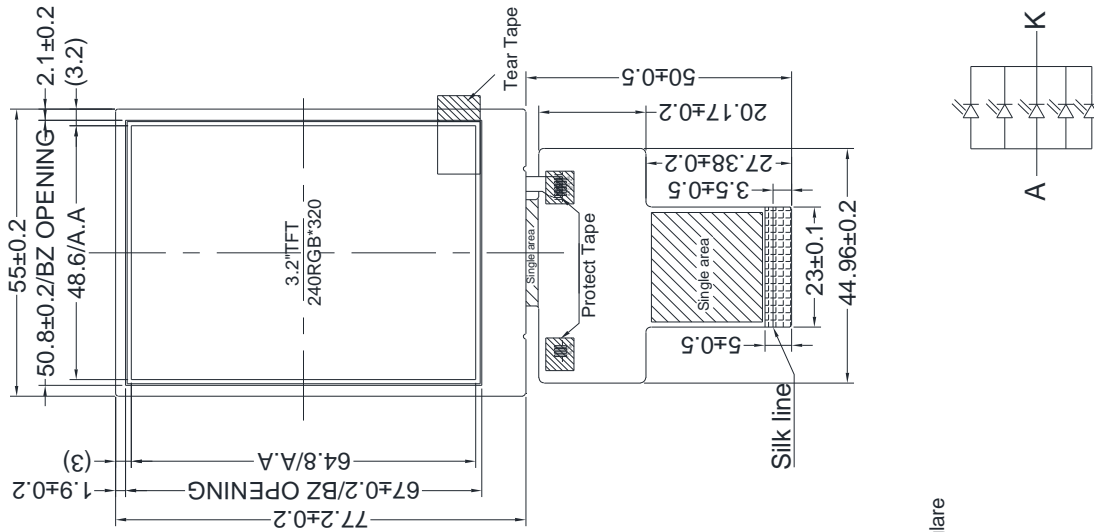
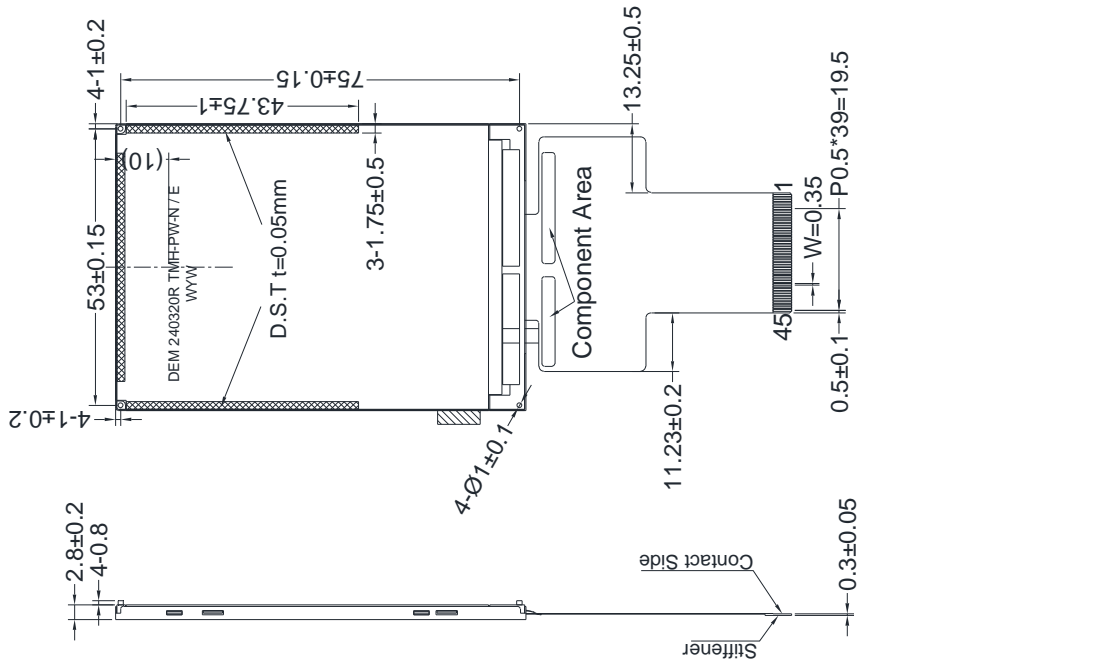
12.6.Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7.Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Outline Drawing



PIN ASSIGNMENT	PIN	ASSIGNMENT
1	EXTC	24 DB15
2	IOVCC(1.8/2.8V)	25 DB16
3	VCC(2.8V)	26 DB17
4	/CS	27 SDA
5	D/C(SCL)	28 SDO
6	/WR	29 TE
7	/RD	30 DOTCLK
8	/RESET	31 VSYNC
9	DB0	32 HSYNC
10	DB1	33 ENABLE
11	DB2	34 IM0
12	DB3	35 IM1
13	DB4	36 IM2
14	DB5	37 IM3
15	DB6	38 NC(YD)
16	DB7	39 NC(XR)
17	DB8	40 NC(YU)
18	DB9	41 NC(XL)
19	DB10	42 LED_A
20	DB11	43 LED_K
21	DB12	44 GND
22	DB13	45 GND
23	DB14	

- NOTES:
1. Display size: 3.2" TFT
 2. Viewing direction: 3 O'CLOCK
 3. Gray Scale inversion direction: 9 O'CLOCK
 3. Display mode: Transmissive/Normal white/Anti-glare
 4. Operation temperature: -20°C~+70°C
 5. Storage temperature: -30°C~+80°C
 6. Driver IC: ILI9341V
 7. Power supply voltage: 2.8V
 8. Backlight : white(5 LED)/3.2(TYP)V/100mA
 9. Brightness: 350cd/m²(TYP)
LED Life: 20Khrs(Min) 30Khrs(Typ)
 10. ROHS must be complied
- * Unspecification tolerance are ± 0.2mm
* The dimension with mark brackets "() " just for reference